

IN THE CLAIMS:

Claims 3, 6 and 7 have been amended herein. All of the pending claims 1 through 7 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Previously presented) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on the upper surface and the lower surface of the substrate;
patternning the layer of copper on at least one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of metal on at least a portion of the layer of copper;
connecting one end of a conductive lead of a TAB tape to the at least one layer of metal; and
consumming a portion of the at least one layer of metal during the connecting of one end of a conductive lead of a TAB tape for connecting at least a portion of one end of the conductive lead of the TAB tape to at least a portion of the layer of copper.

2. (Previously presented) The method of claim 1, further comprising:
connecting one end of the conductive lead of the TAB tape to the at least one layer of metal using a wire bond.

3. (Currently amended) A method of forming a semiconductor device assembly, said method comprising:

providing a substrate having an upper surface and a lower surface;

depositing a layer of copper on the upper surface and the lower surface of the substrate;

patternning the layer of copper on both the upper surface and the lower surface of the substrate to form at least one bond pad thereon;

depositing at least one layer of gold metal on at least a portion of the layer of copper;

connecting one end of a conductive lead of a TAB tape to the at least one layer of gold metal; and consuming a portion of the at least one layer of gold metal during the connecting of one end of a conductive lead of a TAB tape for connecting at least a portion of one end of the conductive lead of the TAB tape to at least a portion of the layer of copper.

4. (Previously presented) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising:

depositing a layer of copper on the upper surface and the lower surface of the substrate;

patternning the layer of copper on the upper surface and the lower surface of the substrate to form at least one bond pad thereon;

depositing at least one layer of metal on at least a portion of the layer of copper;

connecting one end of a conductive lead of a TAB tape to the at least one layer of metal; and consuming a portion of the at least one layer of metal during the connecting of one end of a conductive lead of a TAB tape for connecting at least a portion of one end of the conductive lead of the TAB tape to at least a portion of the layer of copper.

5. (Previously presented) The method of claim 4, further comprising:

connecting one end of the conductive lead of the TAB tape to the at least one layer of metal using a wire bond.

6. (Currently amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on more than one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper on the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of gold metal on at least a portion of the layer of copper; connecting one end of a conductive lead of a TAB tape to the at least one layer of gold metal; and consuming a portion of the at least one layer of gold metal during the connecting of one end of a conductive lead of a TAB tape for connecting at least a portion of one end of the conductive lead of the TAB tape to at least a portion of the layer of copper.

7. (Currently amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on more than one desired surface of one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper on at least one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of gold metal on at least a portion of the layer of copper; connecting one ~~of an~~ end of a conductive lead of a TAB tape and a portion of a bond wire to the at least one layer of gold metal; and consuming a portion of the at least one layer of gold metal during the connecting of one end of a conductive lead of a TAB tape for connecting at least a portion of one end of the conductive lead of the TAB tape to at least a portion of the layer of copper.